

ABSTRACT OF THE DISCLOSURE

A wiring board for a semiconductor device includes a wiring
5 section disposed on an insulation board and an electromagnetic
shielding film disposed at a position close to the wiring
section. A distance defined between the wiring section and the
electromagnetic shielding film is 50 μm or less and a volume
specific resistance of said electromagnetic shielding film is
10 30 $\mu\Omega\cdot\text{cm}$ or less at a room temperature. This structure
reduces an inductance of the wiring section and inductive cross
talk at frequencies between about 10 MHz to 15GHz.